

Integrated Device Technology, Inc.

CMOS STATIC RAM 256K (32K x 8-BIT)

IDT71256SA

FEATURES:

- 32K x 8 advanced high-speed CMOS static RAM
- Equal access and cycle times
 - Military: 15/20/25ns
 - Commercial: 12/15/20/25ns
- One Chip Select plus one Output Enable pin
- Bidirectional data inputs and outputs directly TTL-compatible
- Low power consumption via chip deselect
- Military product compliant to MIL-STD-883, Class B
- Available in 28-pin Sidebraze DIP, Plastic DIP, Plastic SOJ, and 32-pin LCC packages

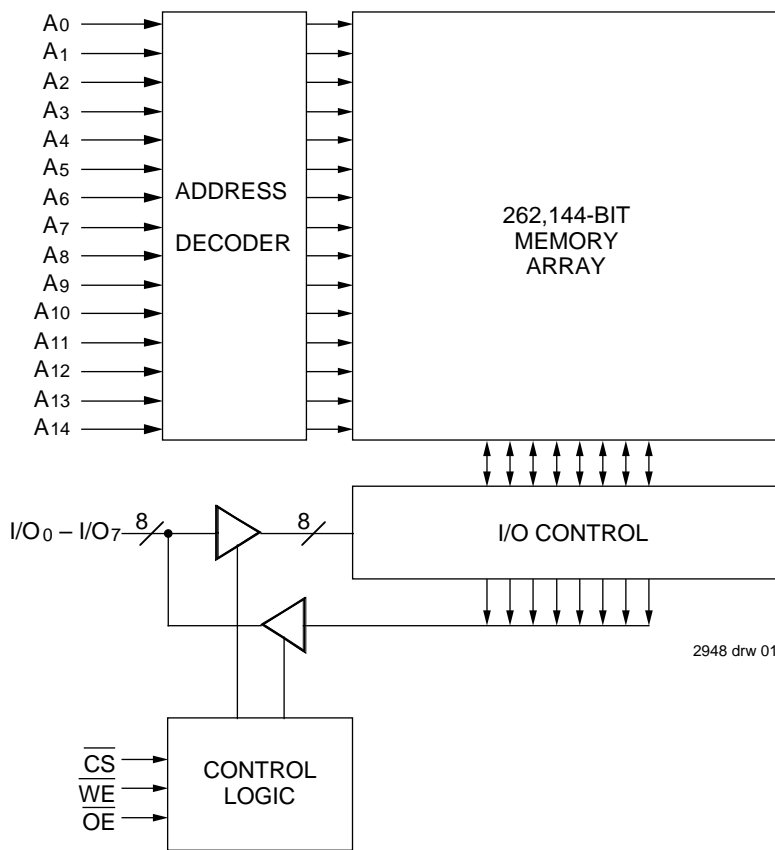
DESCRIPTION:

The IDT71256SA is a 262,144-bit high-speed Static RAM organized as 32K x 8. It is fabricated using IDT's high-performance, high-reliability CMOS technology. This state-of-the-art technology, combined with innovative circuit design techniques, provides a cost-effective solution for high-speed memory needs.

The IDT71256SA has an output enable pin which operates as fast as 6ns, with address access times as fast as 12ns. All bidirectional inputs and outputs of the IDT71256SA are TTL-compatible and operation is from a single 5V supply. Fully static asynchronous circuitry is used, requiring no clocks or refresh for operation.

The IDT71256SA is packaged in 28-pin 300 mil Sidebraze DIP, 28-pin 300 mil Plastic DIP, 28-pin 300 mil Plastic SOJ, and 32-pin Leadless Chip Carrier packages.

FUNCTIONAL BLOCK DIAGRAM

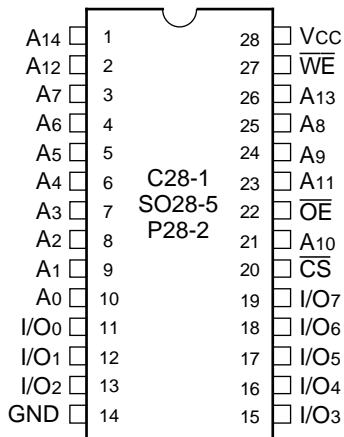


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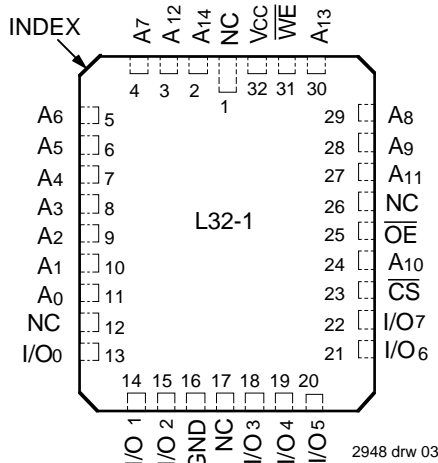
MILITARY AND COMMERCIAL TEMPERATURE RANGES

MAY 1994

PIN CONFIGURATIONS



DIP/SOJ
TOP VIEW 2948 drw 02



LCC
TOP VIEW 2948 drw 03

RECOMMENDED DC OPERATING CONDITIONS

Symbol	Parameter	Min.	Typ.	Max.	Unit
VCC	Supply Voltage	4.5	5.0	5.5	V
GND	Supply Voltage	0	0	0	V
VIH	Input High Voltage	2.2	—	VCC+0.5	V
VIL	Input Low Voltage	-0.5 ⁽¹⁾	—	0.8	V

NOTE: 1. VIL (min.) = -1.5V for pulse width less than 10ns, once per cycle. 2948 tbl 04

DC ELECTRICAL CHARACTERISTICS

VCC = 5.0V ± 10%

Symbol	Parameter	Test Condition	IDT71256SA		Unit
			Min.	Max.	
ILI	Input Leakage Current	VCC = Max., VIN = GND to VCC	—	5	μA
ILO	Output Leakage Current	VCC = Max., CS = VIH, VOUT = GND to VCC	—	5	μA
VOL	Output Low Voltage	IOL = 8mA, VCC = Min.	—	0.4	V
VOH	Output High Voltage	IOH = -4mA, VCC = Min.	2.4	—	V

2948 tbl 05

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Rating	Com'l.	Mil.	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
TA	Operating Temperature	0 to +70	-55 to +125	°C
TBIAS	Temperature Under Bias	-55 to +125	-65 to +135	°C
TSTG	Storage Temperature	-55 to +125	-65 to +150	°C
PT	Power Dissipation	1.0	1.0	W
IOUT	DC Output Current	50	50	mA

NOTES: 2948 tbl 02
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. VTERM must not exceed VCC + 0.5V.

CAPACITANCE

(TA = +25°C, f = 1.0MHz, SOJ package)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	11	pF
CIO	I/O Capacitance	VOUT = 3dV	11	pF

NOTE: 2948 tbl 03
1. This parameter is guaranteed by device characterization, but not production tested.

TRUTH TABLE^(1,2)

CS	OE	WE	I/O	Function
L	L	H	DATAOUT	Read Data
L	X	L	DATAIN	Write Data
L	H	H	High-Z	Outputs Disabled
H	X	X	High-Z	Deselected — Standby (ISB)
VHC ⁽³⁾	X	X	High-Z	Deselected — Standby (ISB1)

NOTES: 2948 tbl 01
1. H = VIH, L = VIL, x = Don't care.
2. V_{LC} = 0.2V, V_{HC} = VCC - 0.2V.
3. Other inputs ≥ VHC or ≤ V_{LC}.

DC ELECTRICAL CHARACTERISTICS⁽¹⁾

(VCC = 5.0V ± 10%, VLC = 0.2V, VHC = VCC–0.2V)

Symbol	Parameter	71256SA12		71256SA15		71256SA20		71256SA25		Unit
		Com'l.	Mil.	Com'l.	Mil.	Com'l.	Mil.	Com'l.	Mil.	
ICC	Dynamic Operating Current CS ≤ VIL, Outputs Open, VCC = Max., f = fMAX ⁽²⁾	160	—	150	170	145	150	145	150	mA
ISB	Standby Power Supply Current (TTL Level) CS ≥ VIH, Outputs Open, VCC = Max., f = fMAX ⁽²⁾	50	—	40	50	40	45	40	45	mA
ISB1	Standby Power Supply Current (CMOS Level) CS ≥ VHC, Outputs Open, VCC = Max., f = 0 ⁽²⁾ VIN ≤ VLC or VIN ≥ VHC	15	—	15	30	15	30	15	30	mA

NOTES:

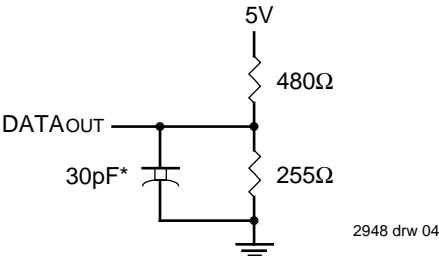
1. All values are maximum guaranteed values.
2. fMAX = 1/trc (all address inputs are cycling at fMAX); f = 0 means no address input lines are changing .

2948 tbl 06

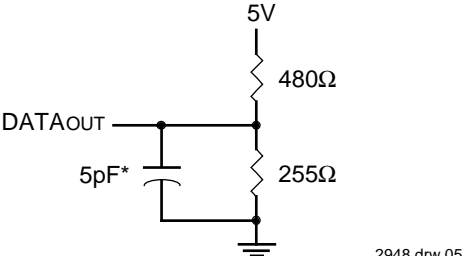
AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
AC Test Load	See Figures 1 and 2

2948 tbl 07



2948 drw 04



2948 drw 05

*Including jig and scope capacitance.

Figure 1. AC Test Load

Figure 2. AC Test Load
(for tCLZ, tOLZ, tCHZ, tOHZ, tOW, and tWHZ)

AC ELECTRICAL CHARACTERISTICS (VCC = 5.0V ± 10%, All Temperature Ranges)

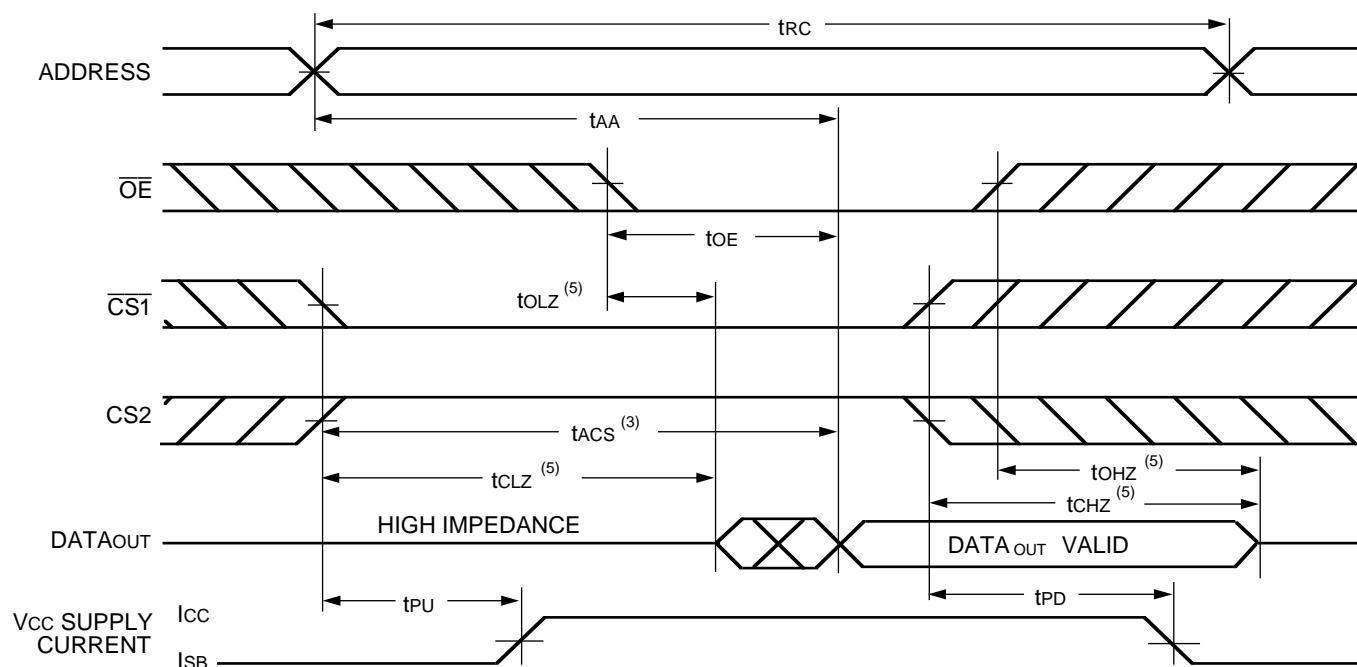
Symbol	Parameter	71256SA12 ⁽¹⁾		71256SA15		71256SA20		71256SA25		
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Read Cycle										
tRC	Read Cycle Time	12	—	15	—	20	—	25	—	ns
tAA	Address Access Time	—	12	—	15	—	20	—	25	ns
tACS	Chip Select Access Time	—	12	—	15	—	20	—	25	ns
tCLZ ⁽²⁾	Chip Select to Output in Low-Z	4	—	4	—	4	—	4	—	ns
tCHZ ⁽²⁾	Chip Deselect to Output in High-Z	0	6	0	7	0	10	0	11	ns
tOE	Output Enable to Output Valid	—	6	—	7	—	10	—	11	ns
tOLZ ⁽²⁾	Output Enable to Output in Low-Z	0	—	0	—	0	—	0	—	ns
tOHZ ⁽²⁾	Output Disable to Output in High-Z	0	6	0	6	0	8	0	10	ns
tOH	Output Hold from Address Change	3	—	3	—	3	—	3	—	ns
tPU ⁽²⁾	Chip Select to Power Up Time	0	—	0	—	0	—	0	—	ns
tPD ⁽²⁾	Chip Deselect to Power Down Time	—	12	—	15	—	20	—	25	ns
Write Cycle										
tWC	Write Cycle Time	12	—	15	—	20	—	25	—	ns
tAW	Address Valid to End of Write	9	—	10	—	15	—	20	—	ns
tcW	Chip Select to End of Write	9	—	10	—	15	—	20	—	ns
tAS	Address Set-up Time	0	—	0	—	0	—	0	—	ns
tWP	Write Pulse Width	9	—	10	—	15	—	20	—	ns
tWR	Write Recovery Time	0	—	0	—	0	—	0	—	ns
tdW	Data Valid to End of Write	6	—	7	—	11	—	13	—	ns
tdH	Data Hold Time	0	—	0	—	0	—	0	—	ns
tOW ⁽²⁾	Output Active from End of Write	4	—	4	—	4	—	4	—	ns
tWHZ ⁽²⁾	Write Enable to Output in High-Z	0	6	0	6	0	10	0	11	ns

NOTES:

- 0° to +70°C temperature range only.
- This parameter is guaranteed with the AC Load (Figure 2) by device characterization, but is not production tested.

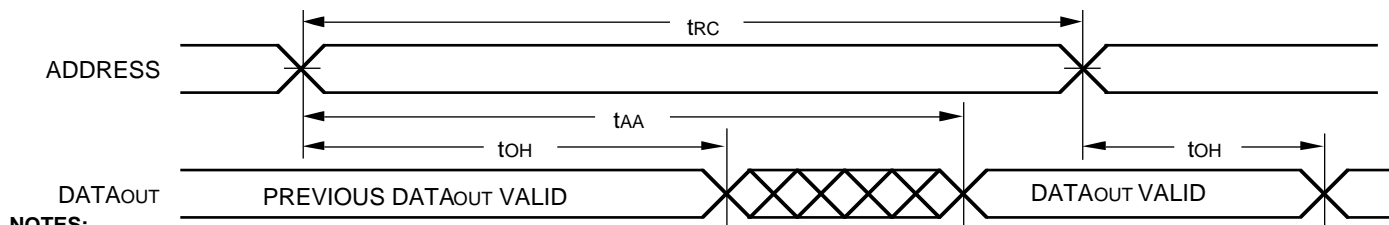
2948 tbl 08

TIMING WAVEFORM OF READ CYCLE NO. 1⁽¹⁾



2948 drw 06

TIMING WAVEFORM OF READ CYCLE NO. 2^(1,2,4)

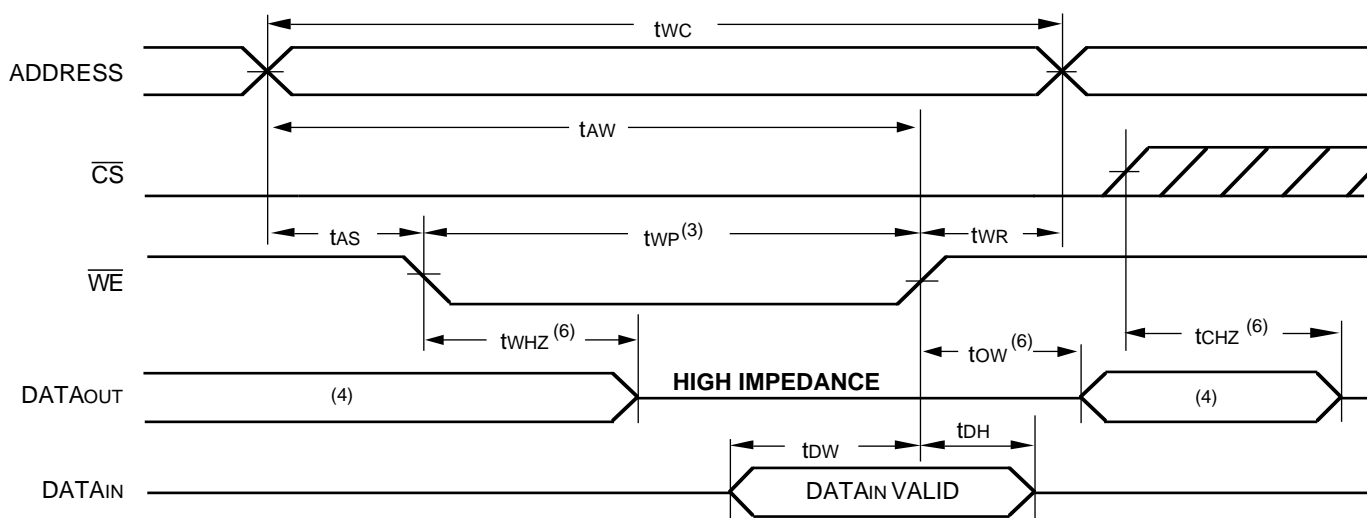


NOTES:

1. \overline{WE} is HIGH for Read Cycle.
2. Device is continuously selected, \overline{CS} is LOW.
3. Address must be valid prior to or coincident with the later of \overline{CS} transition LOW; otherwise t_{AA} is the limiting parameter.
4. \overline{OE} is LOW.
5. Transition is measured $\pm 200\text{mV}$ from steady state.

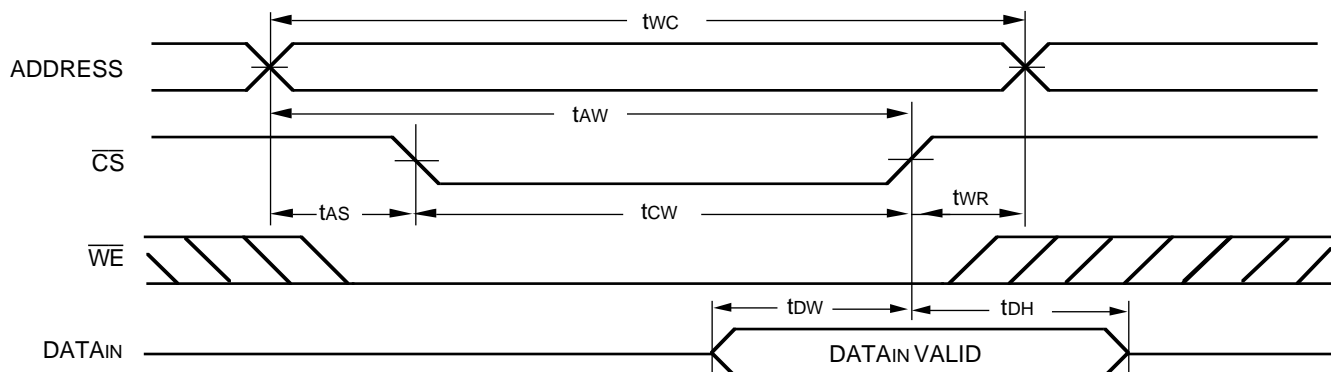
2948 drw 07

TIMING WAVEFORM OF WRITE CYCLE NO.1 (\overline{WE} CONTROLLED TIMING)^(1,2,3,5)



2948 drw 08

TIMING WAVEFORM OF WRITE CYCLE NO.2 (\overline{CS} CONTROLLED TIMING)^(1,2,5)

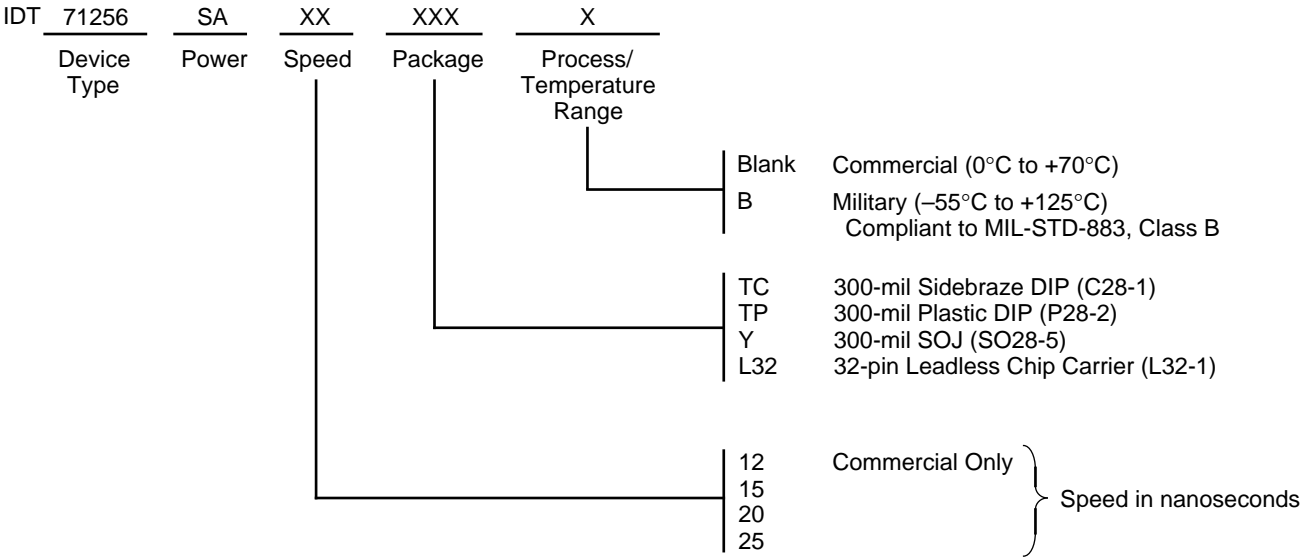


NOTES:

1. \overline{WE} or \overline{CS} must be HIGH during all address transitions.
2. A write occurs during the overlap of a LOW \overline{CS} and a LOW \overline{WE} .
3. \overline{OE} is continuously HIGH. If during a \overline{WE} controlled write cycle \overline{OE} is LOW, t_{WP} must be greater than or equal to $t_{WHZ} + t_{DW}$ to allow the I/O drivers to turn off and data to be placed on the bus for the required t_{OW} . If \overline{OE} is HIGH during a \overline{WE} controlled write cycle, this requirement does not apply and the minimum write pulse is as short as the specified t_{WP} .
4. During this period, I/O pins are in the output state, and input signals must not be applied.
5. If the \overline{CS} LOW transition occurs simultaneously with or after the \overline{WE} LOW transition, the outputs remain in a high-impedance state.
6. Transition is measured $\pm 200\text{mV}$ from steady state.

2948 drw 09

ORDERING INFORMATION



2948 drw 10